

SCS:JW P E
05/13/02 6319-56134

1765
PATENT
Attorney Reference No. 6319-56134

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Chang, Chin-Huang

Art Unit: 1765

Application No.: 09/660,753

Filed: September 13, 2000

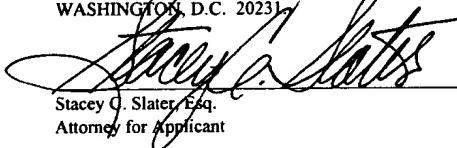
For: METHOD FOR REDUCING SIZE OF
SEMICONDUCTOR UNIT IN PACKAGING
PROCESS

Examiner: Vinh, Lan

Date: May 13, 2002

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on May 13, 2002, as First Class Mail in an envelope addressed to:
BOX NON-FEE AMENDMENT, COMMISSIONER FOR PATENTS,
WASHINGTON, D.C. 20231


Stacey Q. Slater, Esq.
Attorney for Applicant

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Enclosed is an Amendment for the above application. The fee has been calculated as shown below.

CLAIMS AS AMENDED

For	No. after amendment	No. paid for previously	Present Extra	Rate	Fee
Total Claims	20	- 20*	= 0	\$18.00	\$ 0.00
Indep. Claims	3	- 3**	= 0	\$84.00	\$ 0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

* greater of twenty or number for which fee has been paid.

** greater of three or number for which fee has been paid.

No additional fee is required.

Please charge any additional fees that may be required in connection with filing this amendment and any extension of time, or credit any overpayment, to Deposit Account No. 02-4550. A copy of this sheet is enclosed.

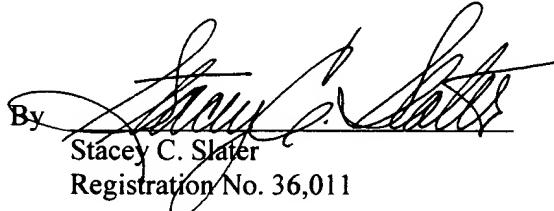
A Marked-up Version of Amended Claims Pursuant to 37 C.F.R. §§ 1.121(b)-(c) is attached.

Please return the enclosed postcard to confirm that the items listed above have been received.

Respectfully submitted,

KLARQUIST SPARKMAN, LLP

By


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cc: Docketing

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For: METHOD FOR REDUCING SIZE OF SEMICONDUCTOR UNIT IN PACKAGING PROCESS

Stacey C. Stater, Esq.
Attorney for Applicant

Examiner: Vinh, Lan

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Washington, D.C. 20231

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AMENDMENT

This responds to the Office action dated February 13, 2002, concerning the application referenced above. Please amend the application as follows.

In the Claims:

Please amend claims as follows:

1. (Amended) A method for reducing the size of at least a semiconductor unit in a process of making a package including a carrier and said semiconductor unit, said semiconductor unit including a first surface and a second surface, said method comprising the steps of:

A | D

attaching at least a part of said first surface to said carrier; and

etching said semiconductor unit from said second surface until the size of said semiconductor unit meets an expected specification.

2. (Amended) The method according to claim 1 wherein said semiconductor unit is etched by using beams of light.

3. (Amended) The method according to claim 1 wherein said semiconductor unit is etched by using plasma.